



PIN ASSIGNMENT	
miniSD #1	CD/DAT3
miniSD #2	CMD
miniSD #3	VSS1
miniSD #4	VDD
miniSD #5	CLK
miniSD #6	VSS2
miniSD #7	DAT0
miniSD #8	DAT1
miniSD #9	DAT2
miniSD #10	NC
miniSD #11	NC
miniSD #CD	CD
miniSD #GND	GND

- NOTES:  
1. MATERIAL:  
INSULATOR:  
HIGH TEMPERATURE THERMOPLASTIC,  
UL94V-0, BLACK  
CONTACT: PHOSPHOR BRONZE  
COVER: STAINLESS STEEL, FOG SURFACE  
2. PLATING:  
CONTACT AREA: 50μ" GOLD OVER 50μ" NICKEL  
SOLDER TAIL: 100μ" TIN OVER 50μ" NICKEL

MSDC-W19PA01-11-LF  
LEADFREE  
RoHS Compliant



PART NO. MSDC-W19PA01-11

DWG NO. MSDC-W19PA01-11

CHECKED BY CY

TOLERANCES ARE

FILE NO.

DRAWING BY

.X ± 0.2  
.XX ± 0.1  
.XXX ±  
AWG

DESCRIPTION:

Mini SD Socket  
Push-Push Type, Reverse Mount

煜倫股份有限公司

UNIT / mm

SCALE 1:1

PROJECTION

AREA

REVISIONS

HK

DATE